## **General Description**

The SJD20N045 uses advanced trench technology to provide excellent R<sub>DS(ON)</sub>, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a wide variety of applications.

#### **Features**

- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

#### **Application**

- PWM Applications
- Load Switch
- Power Management

## **Key Performance Parametes**

Parameter	Value	Unit
V <sub>DS</sub>	20	V
R <sub>DS(ON)_TYP</sub>	5.3	mΩ
I <sub>D</sub>	60	А
Q <sub>G</sub>	22.8	nC



## **Package Marking and Ordering Information**

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJD20N045	SJD20N045	TO-252	Tape	\	/	2500 Pcs

## Table 1. Absolute Maximum Ratings (T<sub>C</sub>=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V <sub>DS</sub>	Drain-Source Voltage (V <sub>GS</sub> =0V)	20	V
V <sub>G</sub> s	Gate-Source Voltage (V <sub>DS</sub> =0V)	±12	V
1-	Drain Current-Continuous(Tc=25°C)	63	А
l <sub>D</sub>	Drain Current-Continuous(Tc=100°C)	40	А
I <sub>DM</sub> (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	252	А
P <sub>D</sub>	Maximum Power Dissipation(Tc=25°C)	39	W
PD	Maximum Power Dissipation(Tc=100°C)	15	W
Eas	Avalanche energy (Note 2)	132	mJ
T <sub>J</sub> , T <sub>STG</sub>	Operating Junction and Storage Temperature Range	-55 To 150	°C

## Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
$R_{ heta$ JC	Thermal Resistance, Junction-to- Case		3.2	°C/W



Table 3. Electrical Characteristics (T<sub>J</sub>=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States	-					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	20			V
	7 0	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V T <sub>J</sub> =25°C			1	μA
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V T <sub>J</sub> =125℃			100	μA
Igss	Gate-Body Leakage Current	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.5		0.9	V
<b>g</b> FS	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A	10			S
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A T <sub>J</sub> =25°C		5.3	7	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =2.5V, I <sub>D</sub> =15A T <sub>J</sub> =25°C		6.5	8.6	mΩ
Dynamic Chara	acteristics		J.			
Ciss	Input Capacitance			2246		pF
$C_{oss}$	Output Capacitance	V <sub>DS</sub> =10V,V <sub>GS</sub> =0V, f=1.0MHz		200		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			130		pF
Rg	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz		1.2		Ω
Switching Para	meters		J.			
t <sub>d(on)</sub>	Turn-on Delay Time			13		nS
t <sub>r</sub>	Turn-on Rise Time	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =10V,		32		nS
t <sub>d(off)</sub>	Turn-Off Delay Time	$R_L$ =0.5Ω, $R_{GEN}$ =3Ω		47		nS
t <sub>f</sub>	Turn-Off Fall Time			94		nS
$Q_g$	Total Gate Charge			22.8		nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =10V, I <sub>D</sub> =20A		4.6		nC
$Q_{gd}$	Gate-Drain Charge			7		nC
Source-Drain D	Piode Characteristics		•	•		
I <sub>SD</sub>	Source-Drain Current (Body Diode)				60	А
V <sub>SD</sub>	Forward on Voltage (Note 3)	V <sub>GS</sub> =0V, I <sub>S</sub> =20A			1	V
t <sub>rr</sub>	Reverse Recovery Time	I=20A, dI/dt=100A/μs		11		ns
Qrr	Reverse Recovery Charge	I <sub>F</sub> =20A, dI/dt=100A/μs		2.5		nC

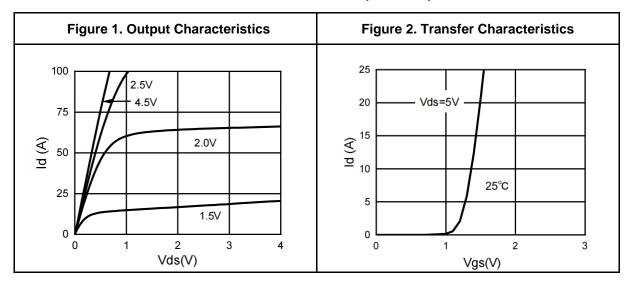
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

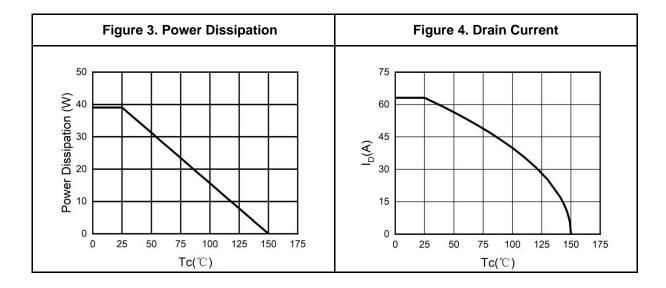
Notes 2.E<sub>AS</sub> condition:  $T_J=25^{\circ}C$ ,  $V_{DD}=10V$ ,  $V_G=10V$ ,  $Rg=25\Omega$ , L=0.5mH.

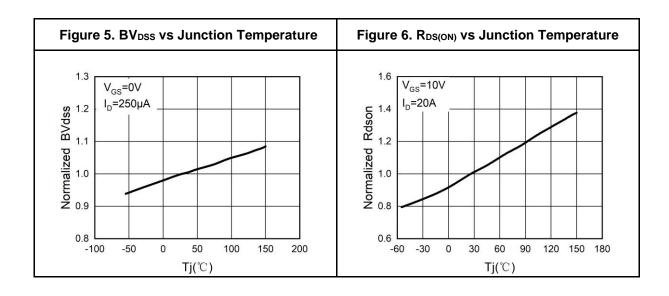
Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



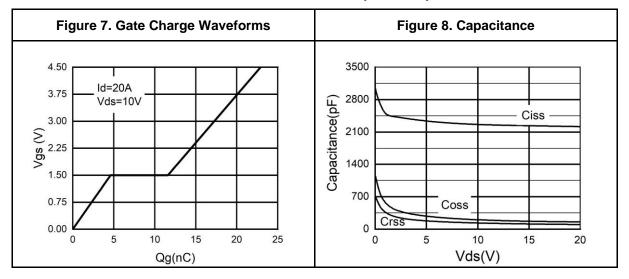
# **Typical Electrical And Thermal Characteristics (Curves)**

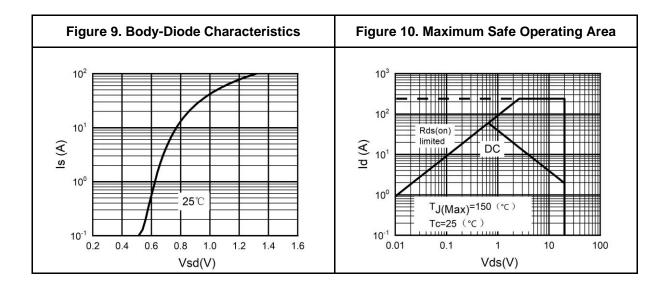






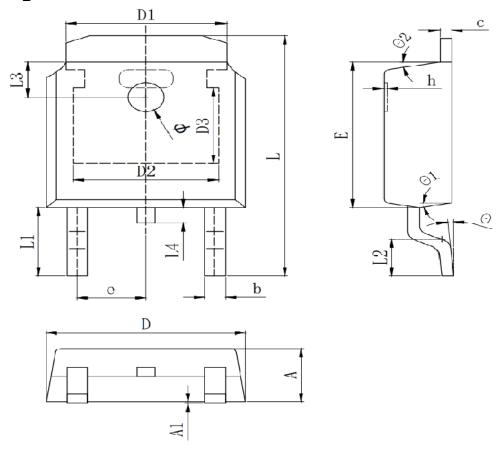
# **Typical Electrical And Thermal Characteristics (Curves)**







# **TO-252 Package Information**



Symbol	Dimensions In Millimeters				
Syllibol	Min.	Тур.	Max.		
А	2.200	2.300	2.400		
A1	0.000		0.127		
b	0.640	0.690	0.740		
c(电镀后)	0.460	0.520	0.580		
D	6.500	6.600	6.700		
D1		5.334 REF			
D2		4.826 REF			
D3		3.166 REF			
E	6.000	6.100	6.200		
е		2.286 TYP			
h	0.000	0.100	0.200		
L	9.900	10.100	10.300		
L1		2.888 REF			
L2	1.400	1.550	1.700		
L3		1.600 REF			
L4	0.600	0.800	1.000		
Ф	1.100	1.200	1.300		
θ	0°		8°		
θ1		9° TYP			
θ2		9° TYP			

#### **Attention**

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor.

The performances and characteristics of this product in the independent testing state are displayed in this document. Wuxi Shangjia Semiconductor can't guarantee of the performances and characteristics of this described product that mounted in the customer's products or equipments as same as that in the independent testing state. So the customer should evaluate and test devices mounted in the customer's products or equipments.

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